AMENDMENTS TO THE SPECIFICATION

Please amend the specification as follows:

Please amend the paragraph on page 6, lines 6-9 as follows:

--The dielectric pellet may be contacted by the conductive feed structure on more than one side, for example on several sides together. In one embodiment, the dielectric pellet may be contained within an electrically conductive cup or cage (e.g., cup or cage 17 in Fig. 18), and the cup or cage may be then fed by the conductive feed structure.--

Please amend the paragraph on page 8, lines 29-31 as follows:

--The dielectric pellet may physically contact the radiating antenna component, or there may be a small air gap or other dielectric spacer material (e.g., material 18 in Fig. 20) between the dielectric pellet and the radiating antenna component.--

Please amend the paragraphs beginning on page 10, line 20 as follows:

--FIGURES 14 and 15 show a single dielectric pellet being used to feed or excite a pair of PILAs; ~~and~~—

FIGURE 16 shows a single dielectric pellet being used to feed a pair of radiating antenna components, one of which is a PILA and the other a PIFA[[.]];--

On page 10, line 25, insert the following paragraphs:

-- FIGURE 17 shows the electrically conductive direct feed structure directly attached to more than one side or surface of the dielectric pellet;

FIGURE 18 shows the dielectric pellet contained in an electrically conductive cup or cage;

FIGURE 19 shows a plurality of dielectric pellets;

FIGURE 20 shows a gap defined between the dielectric pellet and the upper surface of the dielectric substrate; and

FIGURE 21 shows a dielectric spacer material between the surface of the dielectric pellet and the radiating antenna component.--

Please amend the paragraph on page 10, line 26- page 11 line 8 as follows:

--~~Figure~~ FIGS. 1 and 19 ~~shows~~ show a dielectric substrate in the form of a printed circuit board (PCB) 1 having upper 3 and lower 4 surfaces and a conductive groundplane 2, 2' on each of the upper 3 and lower 4 surfaces. The PCB 1 shown in the Figure is suitable for incorporation into a mobile telephone handset (not shown), and the lower surface 4 will generally serve as a support for the various electronic components (not shown) of the mobile telephone. A ceramic dielectric pellet 5 (and 5') is mounted on a conductive direct feed structure 6 (and 6') in the form of a metal ribbon extending upwardly from the upper surface 3 of the PCB 1 in a corner thereof. In this way, the pellet 5 is raised or elevated over the PCB 1 and the groundplane 2 and does not directly contact either of these. The provision of an air gap between the pellet 5 and the groundplane 2 serves to improve bandwidth. The feed 6 is attached by way of soldering to a metallised inner side wall 7 (and 7') of the pellet 5. The other end of the feed 6 is connected to a signal source (not shown).--